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(12) **United States Design Patent**
Osada

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(54) **HOLDING PAD FOR TRANSFERRING A WAFER**

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(**) Term: **14 Years**

(21) Appl. No.: **29/425,303**

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(30) **Foreign Application Priority Data**

Dec. 22, 2011 (JP) D2011-029877

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; 118/500, 724, 725, 728, 729;
414/217, 222.01, 416.03, 935, 936,
414/937, 938, 939, 940, 941
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a holding pad for transferring a wafer, as shown and described.

DESCRIPTION

FIG. 1 is a front view of a holding pad for transferring a wafer showing my new design.

FIG. 2 is a rear view of the holding pad for transferring a wafer of FIG. 1.

FIG. 3 is a top plan view of the holding pad for transferring a wafer of FIG. 1.

FIG. 4 is a bottom plan view of the holding pad for transferring a wafer of FIG. 1.

FIG. 5 is a right side view of the holding pad for transferring a wafer of FIG. 1.

FIG. 6 is a left side view of the holding pad for transferring a wafer of FIG. 1.

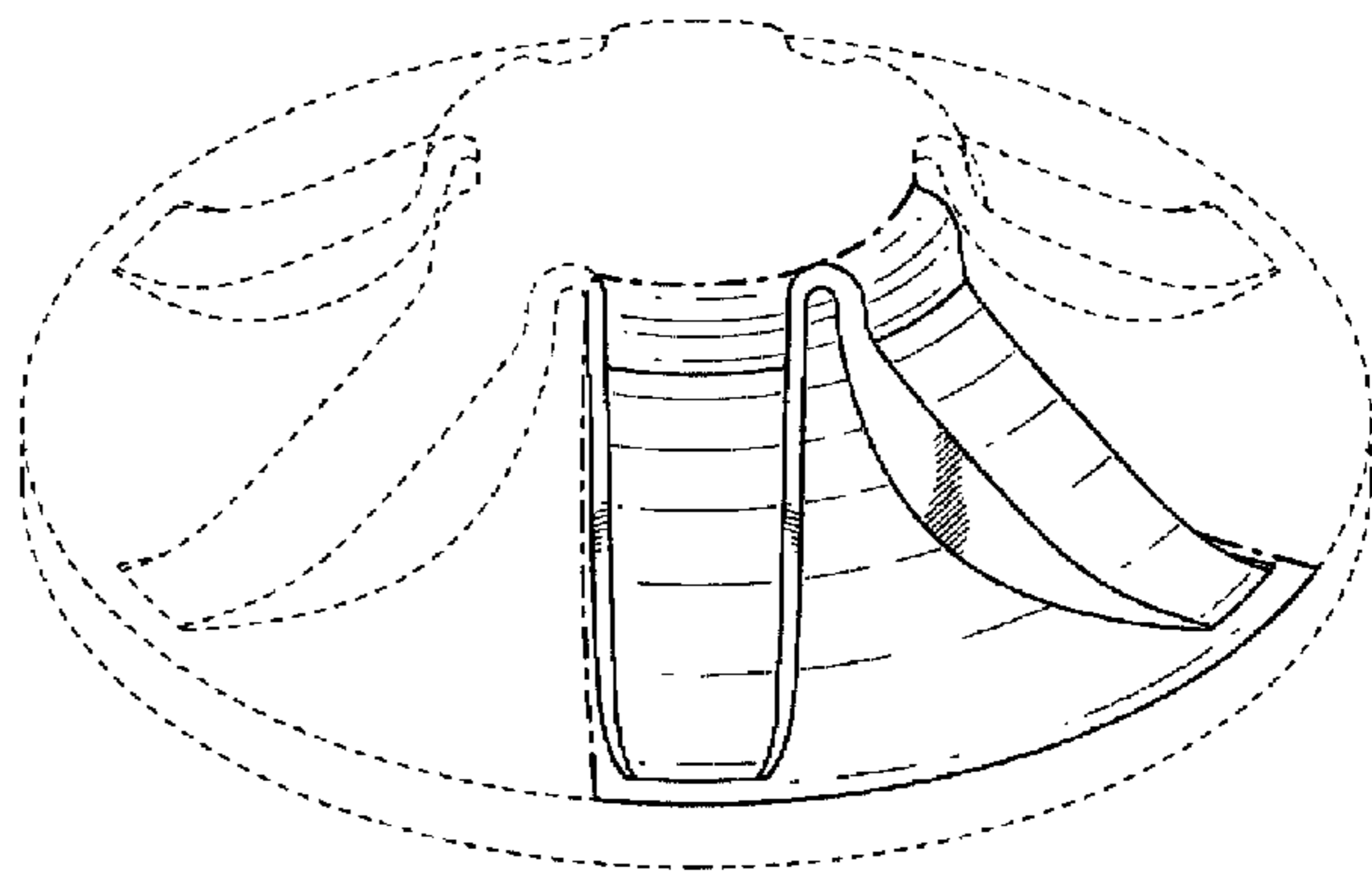
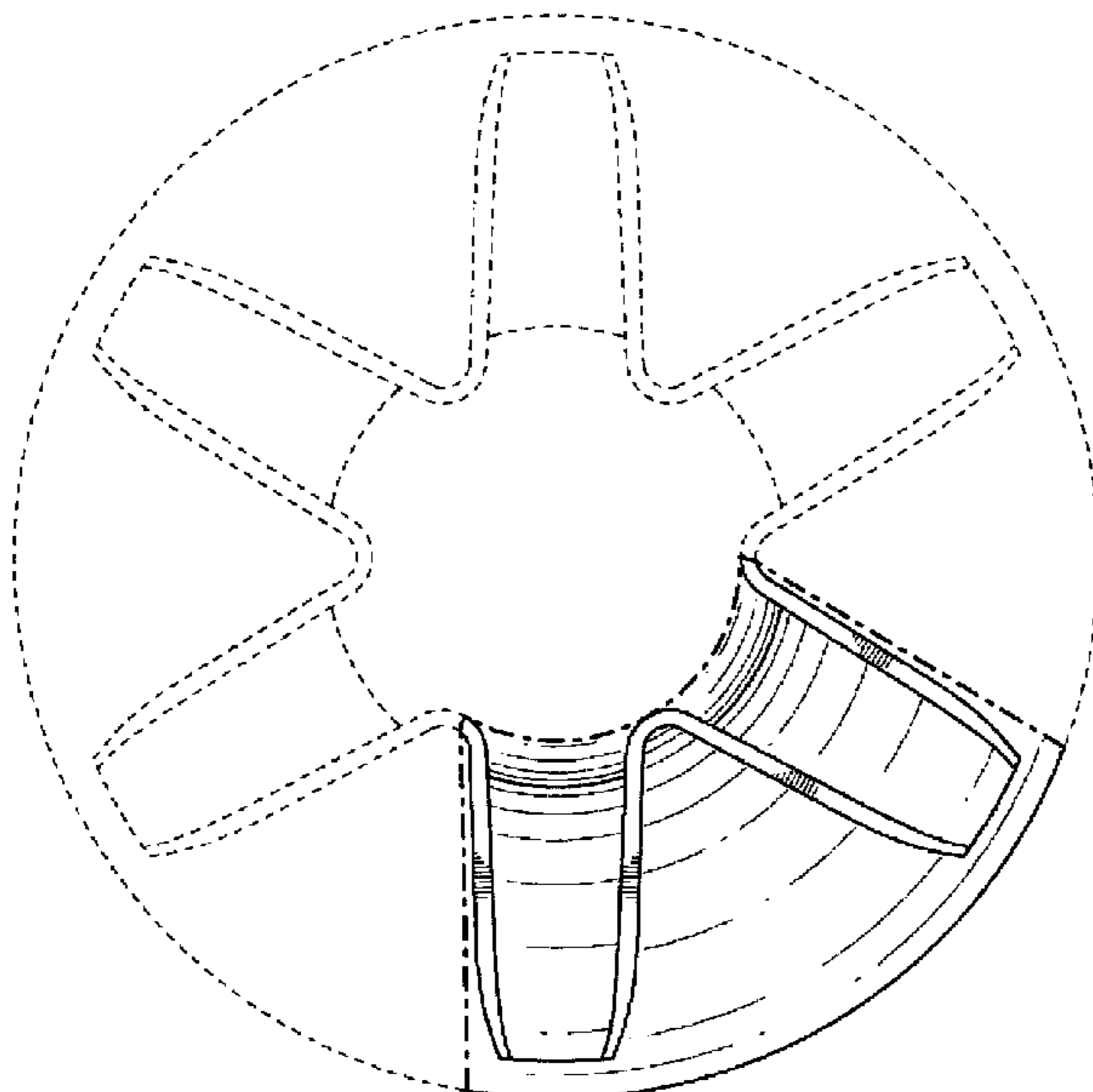
FIG. 7 is a perspective view of the holding pad for transferring a wafer of FIG. 1; and,

FIG. 8 is another front view of the holding pad for transferring a wafer of FIG. 1 shown a used condition.

The features shown in broken lines depict environmental subject matter only and form no part of the claimed design.

The dashed-dot-dashed lines define the boundary lines of the claimed design.

1 Claim, 8 Drawing Sheets



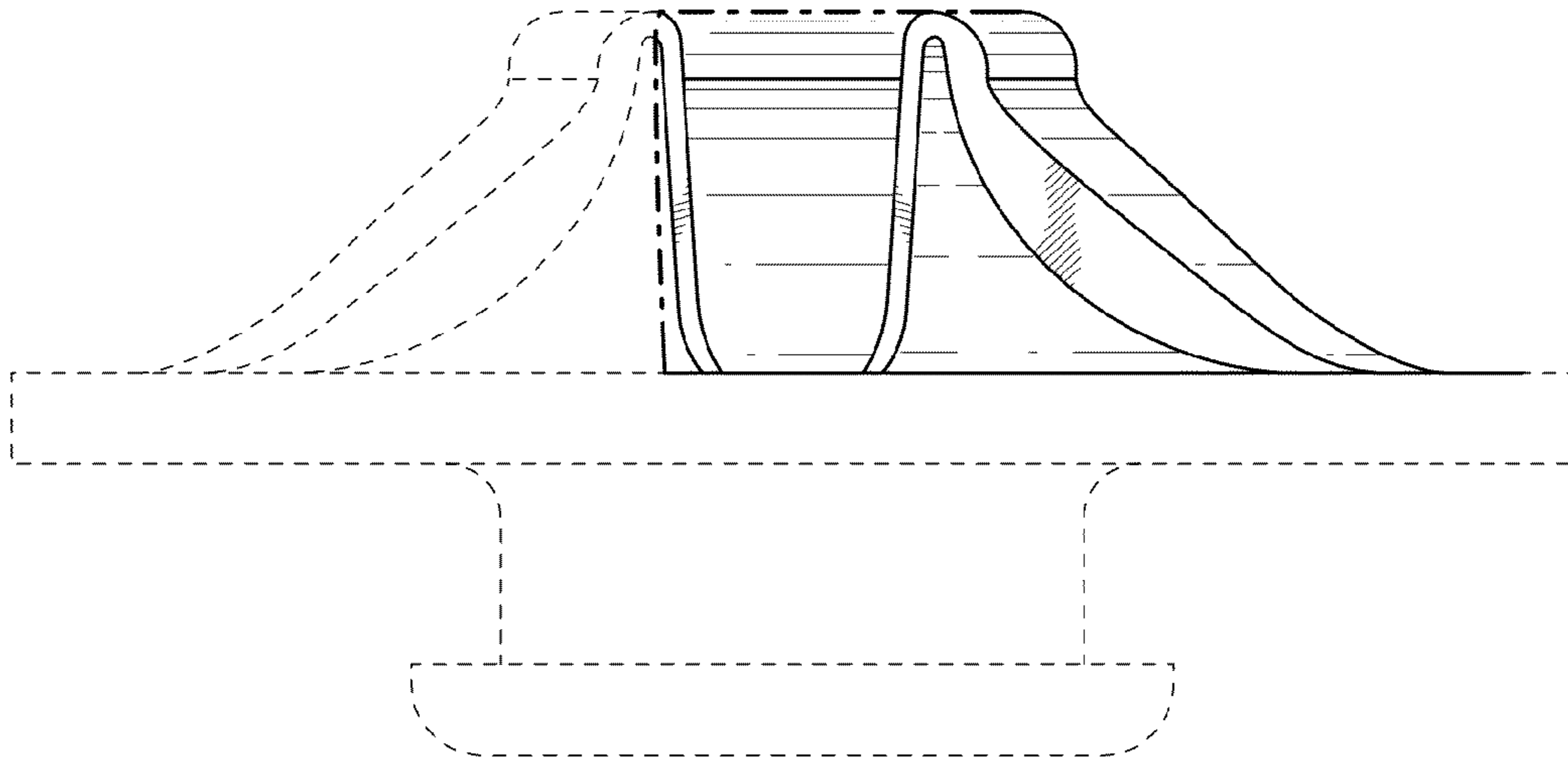


FIG. 1

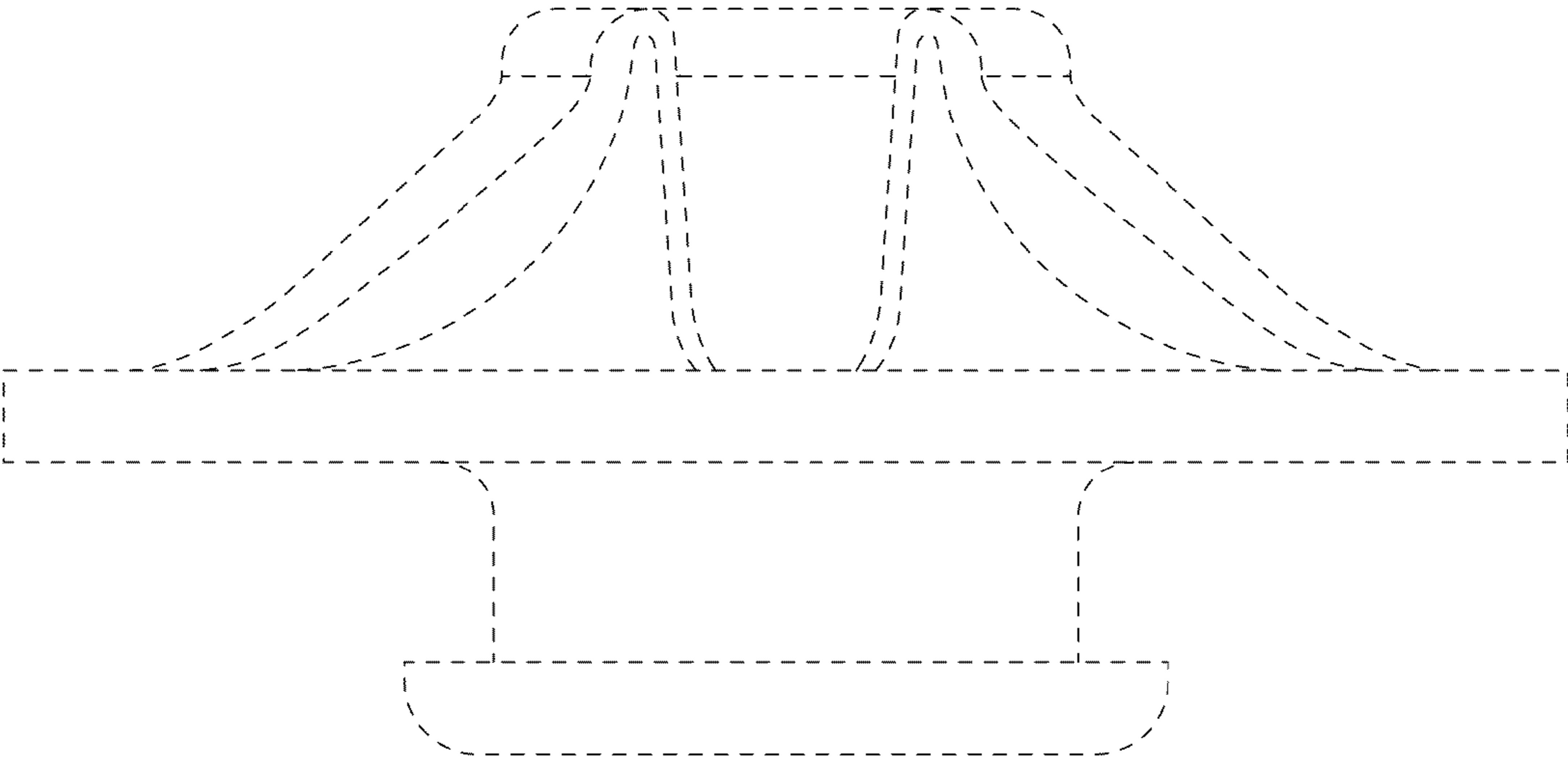


FIG 2

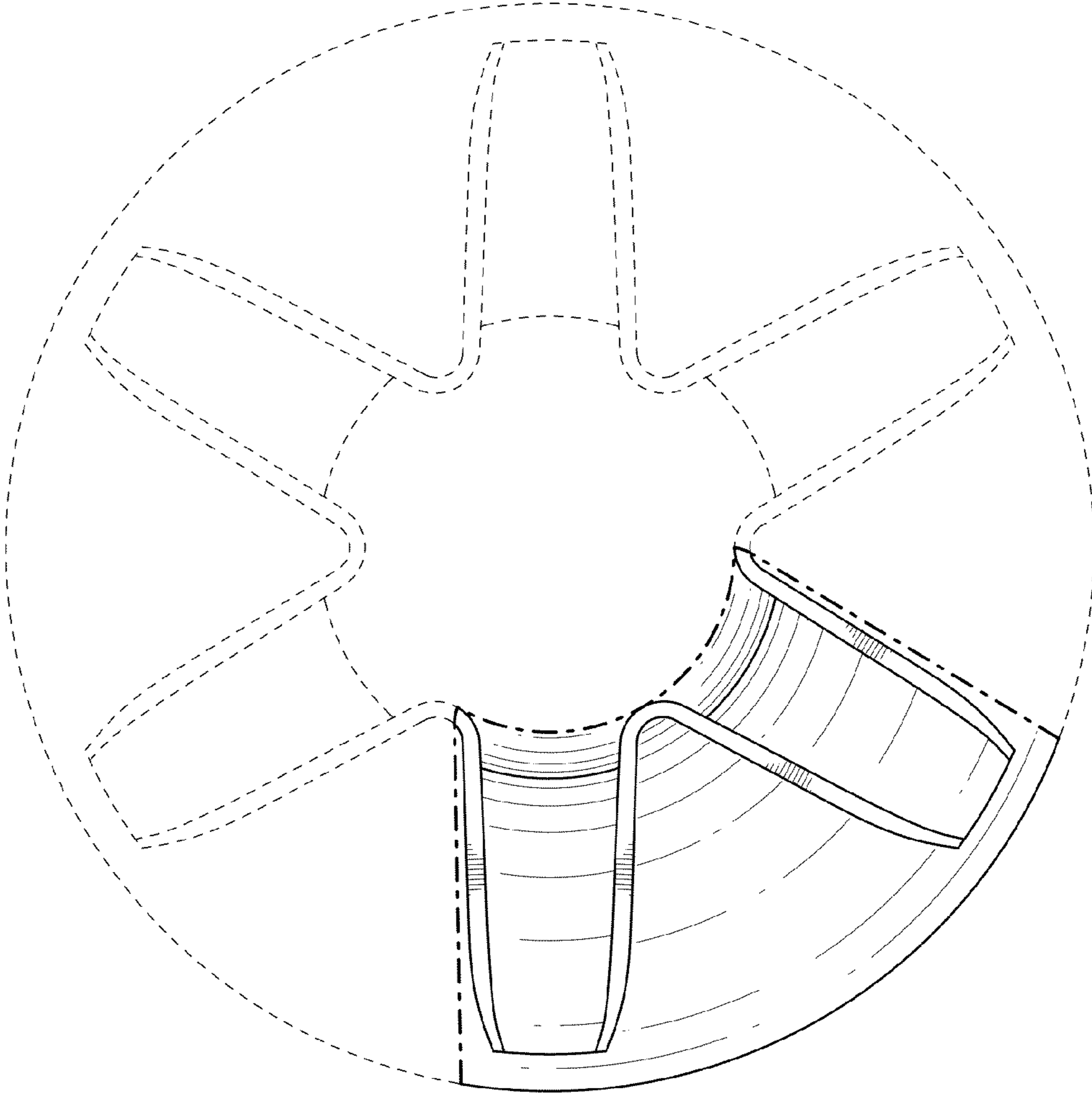


FIG. 3

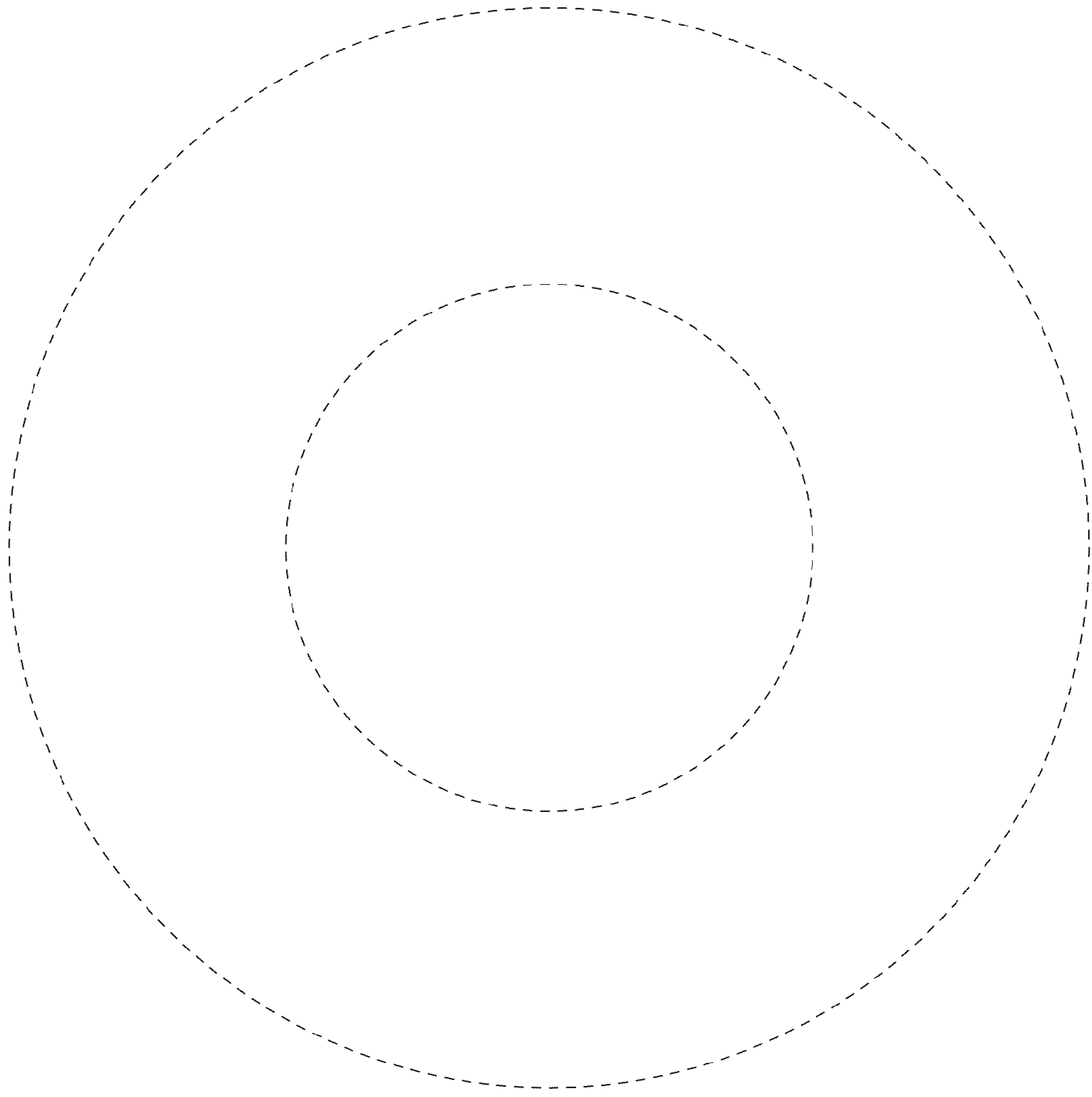


FIG. 4

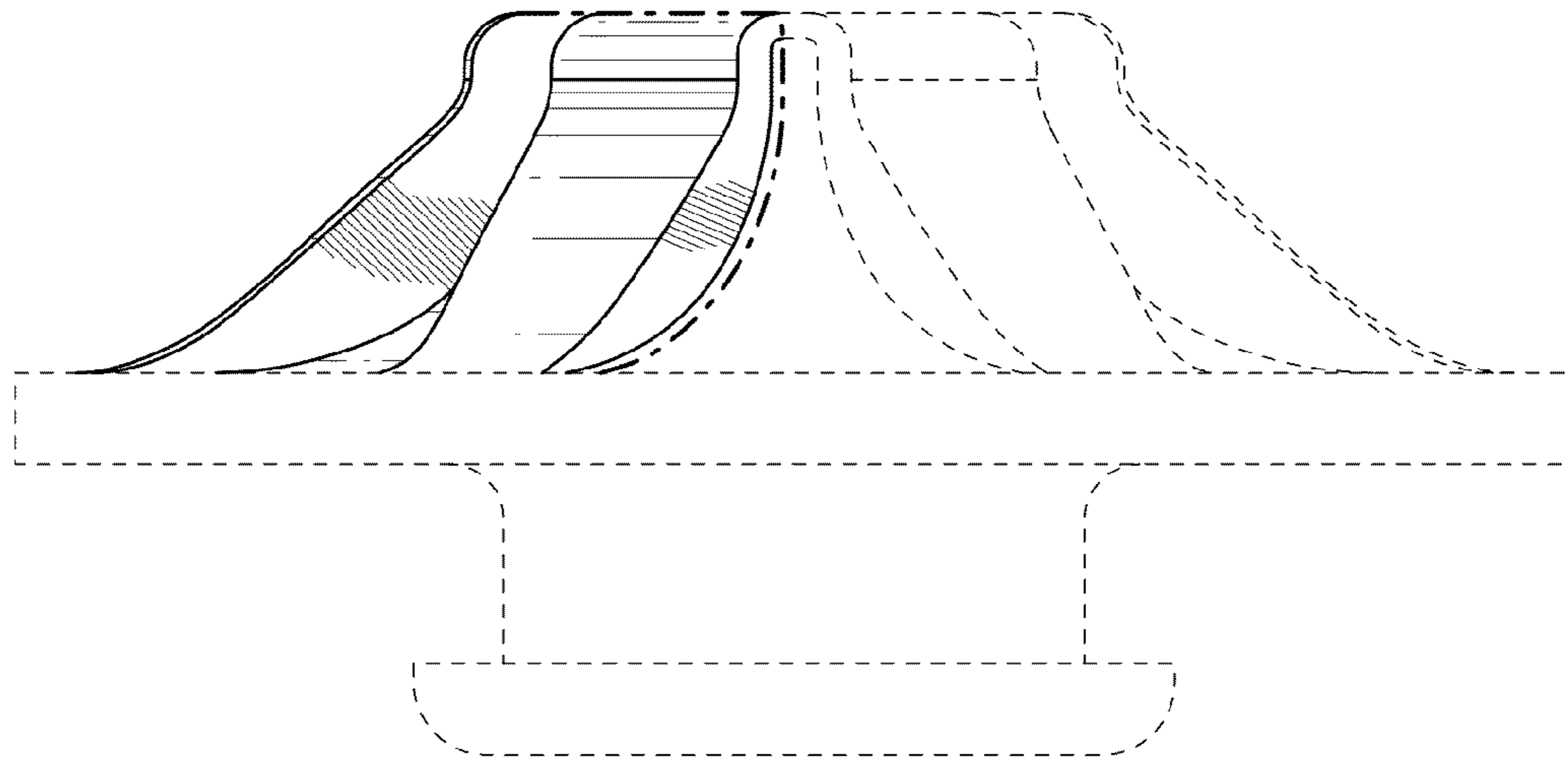


FIG. 5

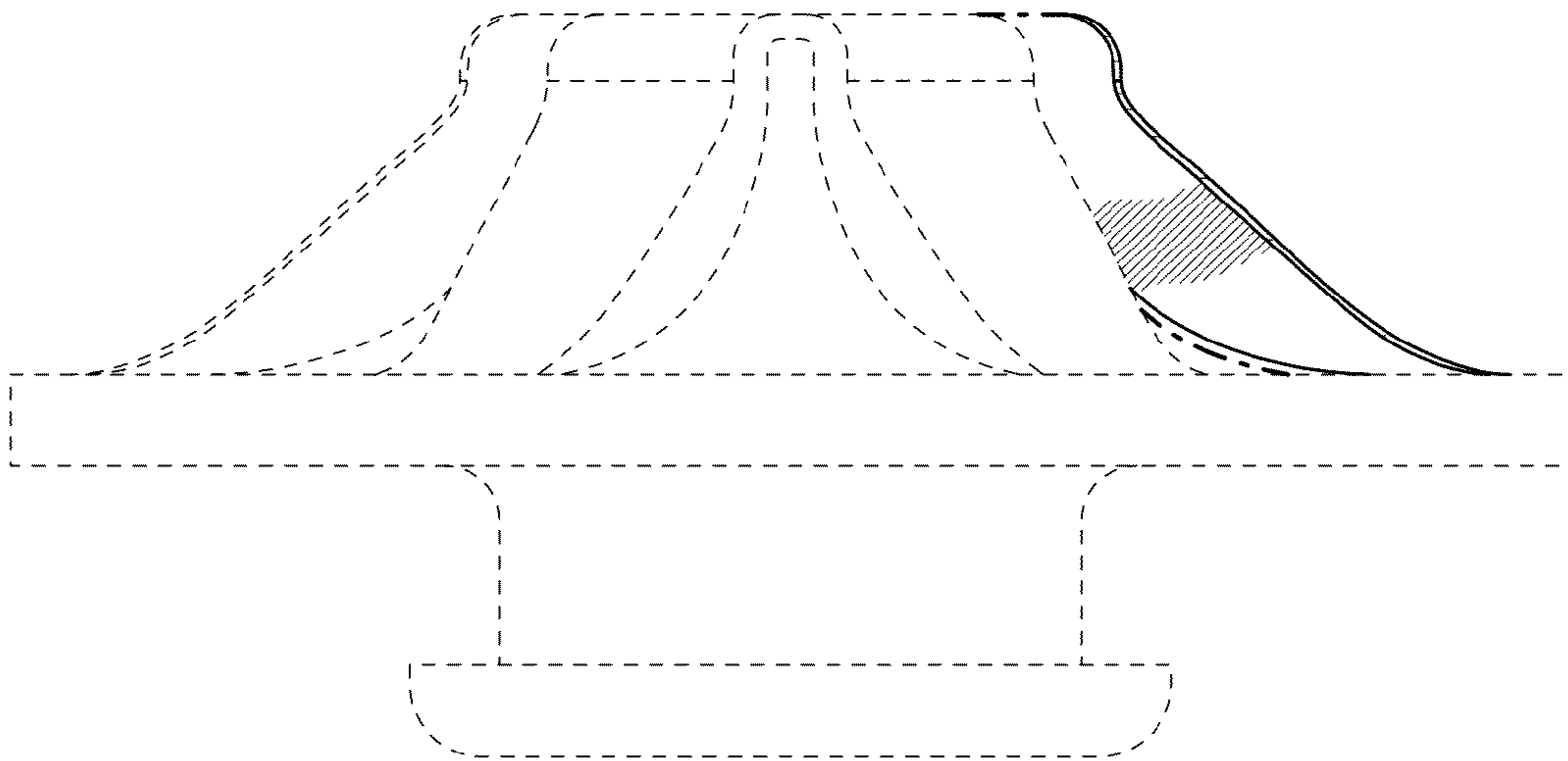


FIG. 6

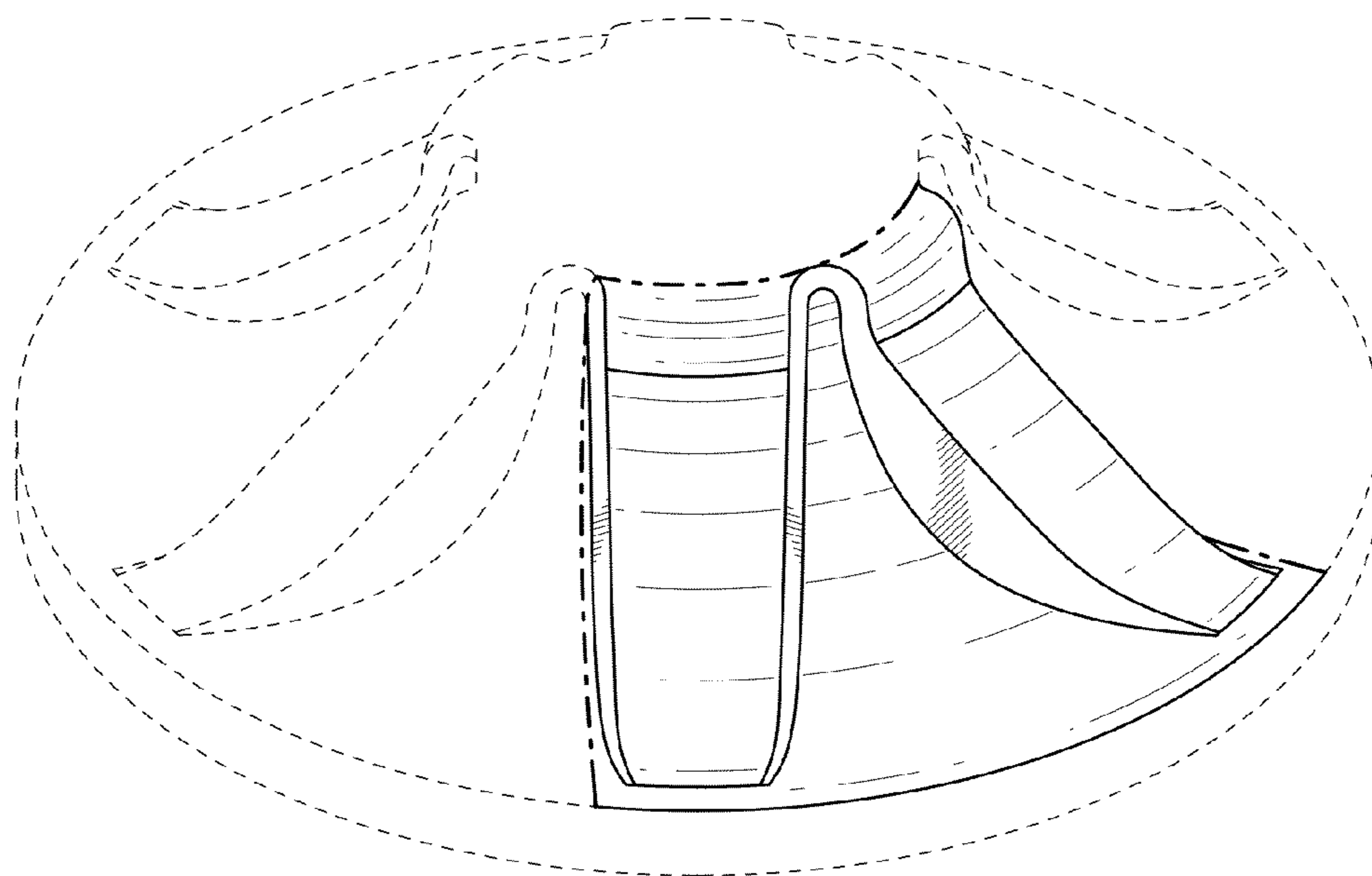


FIG. 7

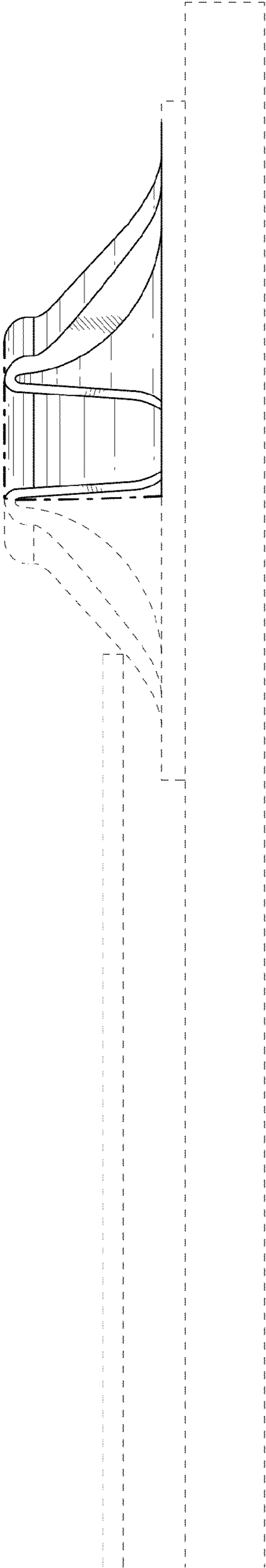


FIG. 8